

elements characteristic of the invention are set forth with particularity in the appended claims. The drawings are for illustration purposes only and are not drawn to scale. Furthermore, like numbers represent like features in the drawings. The invention itself, however, both as to organization and method of operation, may best be understood by reference to the detailed description which follows, taken in conjunction with the accompanying drawings, in which:

[0015] Figures 1(a)–1(d) illustrate a method for forming an interconnect structure in accordance with one embodiment of the present invention;

[0016] Figures 2(a)–2(d) illustrate a method for forming an interconnect structure in accordance with a second embodiment of the present invention;

11/3/04 [0017] Figures 3(a)–3^f(~~e~~) illustrate a method for forming an interconnect structure in accordance with a third embodiment of the present invention;

11/3/04 [0018] Figures 4(a)–4^f(~~e~~) illustrate a method for forming an interconnect structure in accordance with a fourth embodiment of the present invention; and

[0019] Figures 5(a)–5(e) illustrate a prior art method for forming an interconnect structure.